

**Petek, 20. februar 2026**

Pozdravljeni,

tudi v tem tednu vam pošljamo pregled izbranih informacij in novosti s področja čipov, polprevodnikov ter aktivnosti KC Čip.si.

## Aktualno

- **Razpis: Horizon-JU-Chips: HORIZON-JU-Chips 2026-1-RIA**  
Tema naslavlja ključne izzive SRIA Chips JU z osredotočenostjo na integracijo verige elektronskih komponent in sistemov (ECS), interoperabilnost, odprte standarde ter aktivno vključevanje podjetij.  
Rok za oddajo prijav (prva faza): **7. maj 2026 do 17:00**  
Razpis je objavljen na 54. strani programa razpisov Chips JU – ECS na [povezavi](#).  
Celotna dokumentacija razpisa s prihavnimi obrazci je dostopna na [povezavi](#).
- **ChipStart EU Webinar: Join the EU Semiconductor Startup Global Winners of Cohort #2**  
20. februar 2026, 11:30 – 12:30, on-line  
Spletni seminar bo ponudil globok vpogled v edinstven in zelo cenjen podjetniški inkubator za polprevodnike ChipStart EU.  
Dodatne informacije in prijavní obrazec so dostopni na [povezavi](#).
- **Online workshop: The 2026 FAMES Pilot Line Open-Access Call: your pathway to Europe's next generation of chip technologies**  
9. marec 2026, 14:00-16:30, on-line  
Na spletni delavnici bo predstavljeno, kaj lahko pilotna linija FAMES ponudi, katere tehnologije in oprema je na voljo.  
Dodatne informacije in prijavní obrazec so dostopni na [povezavi](#).

## Zanimivosti s področja:

- **[Chips Act spurs semiconductor investments in Europe](#)**  
A year ahead of the revision of the [European Chips Act](#), Europe is investing heavily in its semiconductor ecosystem. But more may be needed.
- **[Infineon phases out GaN System parts](#)**  
Infineon Technologies is phasing out the automotive gallium nitride (GaN) power devices it acquired with GaN Systems as it looks to introduce its own GaN products.

- **Photonic neurons push ultra-fast trading beyond electronic limits**  
Photonic neurons could enable ultra-fast trading by processing data at the speed of light.
- **Can A Computer Science Student Be Taught To Design Hardware?**  
To fill the talent gap, CS majors could be taught to design hardware, and the EE curriculum could be adapted or even shortened.
- **GlobalFoundries and Renesas expand partnership for U.S. chip manufacturing**  
The article highlights how major chip suppliers are responding to ongoing supply risks and rising demand from smart vehicles and industrial automation.
- **Chip Assembler ASE Sees Advanced Packaging Sales Doubling**  
ASE, the world's largest chip assembler, expects its advanced packaging sales to double this year.
- **TSMC considers an additional \$100 billion investment into Arizona fabs to bolster American chipmaking efforts** - move would help TSMC's chips avoid tariffs due to local production \$100 billion investment and four more fab modules.
- **GeSn alloys emerge as a new semiconductor class that could reshape optoelectronics**  
Scientists have created a new type of material that could enable common electronic devices to work faster and use less energy.

Lep pozdrav,  
vaš KC Čip.si



**Slovenski kompetenčni center za čipe in polprevodniške tehnologije**

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Financira  
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REPUBLIKA SLOVENIJA  
MINISTRSTVO ZA DIGITALNO PREOBRAZBO

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To sporočilo ste prejeli, ker ste se prijavljene na prejemanje novic KC Čip.si ali izrazili interes za obveščanje o naših dejavnostih.

Če novic ne želite več prejemati, se lahko kadarkoli odjavite.

[Odjava](#)

